Supplier Name: Contact Info: Form/Declaration Type: Created on:

Texas Instruments Inc. (DUNS# 00-732-1904) ti.com/support Distribute - RoHS and IEC 62474 DB

Distribute - RoHS and II 05/17/2022

Details for "REG103FA-AKTTT"

Current Product Information

| TI part number | Lead finish/Ball material | MSL rating/peak reflow | Assembly site | Package Pins | Package body size (mm) | Total device mass (mg)* |
|----------------|---------------------------|------------------------|---------------|----------------|------------------------|-------------------------|
| REG103FA-AKTTT | SN | Level-2-260C-1 YEAR | Ext-Mfg | KTT 5 | 8.42x10.16x4.58 | 2258.3 |

*Total Device Mass

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value

Environmental Ratings Information

| RoHS | REACH | Green | IEC 62474 DB |
|------|-------|-------|--------------|
| Yes | Yes | Yes | Yes |

Component Information

| | | | | Homogeneous Material Level | | Component Level | |
|------------------------------------|-----------------------|--------------|-------------|----------------------------|---------|-----------------|---------|
| Component | Substance | CAS Number | Amount (mg) | Percentage % | ppm | Percentage % | ppm |
| Bond Wire | | | | | | | |
| Not Categorized | Proprietary Materials | | 0.000048 | 0.007273 | 73 | 0.000002 | 0 |
| Precious Metals | Gold | 7440-57-5 | 0.65996 | 99.992727 | 999927 | 0.029224 | 292 |
| Sub-Total | | | 0.660008 | 100 | 1000000 | 0.029227 | 292 |
| Die Attach Adhesive | | | | | | | |
| Precious Metals | Silver | 7440-22-4 | 0.66469 | 87.000056 | 870001 | 0.029434 | 294 |
| Thermoplastics | Epoxy | 85954-11-6 | 0.099321 | 12.999944 | 129999 | 0.004398 | 44 |
| Sub-Total | | | 0.764011 | 100 | 1000000 | 0.033832 | 338 |
| Lead Frame | | | | | | | |
| Copper and Its Alloys | Copper | 7440-50-8 | 1457.1798 | 99.8 | 998000 | 64.526897 | 645269 |
| Other Nonferrous Metals and Alloys | Tin | 7440-31-5 | 1.4601 | 0.1 | 1000 | 0.064656 | 647 |
| Precious Metals | Silver | 7440-22-4 | 1.4601 | 0.1 | 1000 | 0.064656 | 647 |
| Sub-Total | | | 1460.1 | 100 | 1000000 | 64.65621 | 646562 |
| Lead Frame Plating | | | | | | | |
| Other Nonferrous Metals and Alloys | Tin | 7440-31-5 | 0.0124 | 100 | 1000000 | 0.000549 | 5 |
| Sub-Total | | | 0.0124 | 100 | 1000000 | 0.000549 | 5 |
| Mold Compound | | | | | | | |
| Other Inorganic Materials | Fused Silica | 60676-86-0 | 673.822306 | 84.81 | 848100 | 29.838228 | 298382 |
| Other Nonferrous Metals and Alloys | Metal Hydroxide | Trade Secret | 41.31442 | 5.2 | 52000 | 1.829487 | 18295 |
| Other Plastics and Rubber | Carbon Black | 1333-86-4 | 1.668467 | 0.21 | 2100 | 0.073883 | 739 |
| Thermoplastics | Epoxy | 85954-11-6 | 77.702891 | 9.78 | 97800 | 3.440843 | 34408 |
| Sub-Total | | | 794.508084 | 100 | 1000000 | 35.182441 | 351824 |
| Semiconductor Device | | | | | | | |
| Ceramics / Glass | Doped Silicon | 7440-21-3 | 2.207262 | 100 | 1000000 | 0.097742 | 977 |
| Sub-Total | | | 2.207262 | 100 | 1000000 | 0.097742 | 977 |
| Tatal | | | 2250 254765 | | | 100 | 4000000 |
| Total | | | 2258.251/65 | | | 100 | 1000000 |

Important Note

The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm

for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.

The ppm calculations are at the component level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the component. See Glossary of Terms for more details.

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSIs or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

For an explanation of the methods used to determine material weights, See Product Content Methodology

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

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For additional information, please contact TI customer support.

Signature: (click here for a fuller statement with a signed certificate)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality For further environmental statements, please go to www.ti.com/ecoinfo Created on: 05/17/2022

RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with ADSL and the IEC 62746 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in http://www.ti.com/lit/pdf/szzq088

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet J5709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb203) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.